



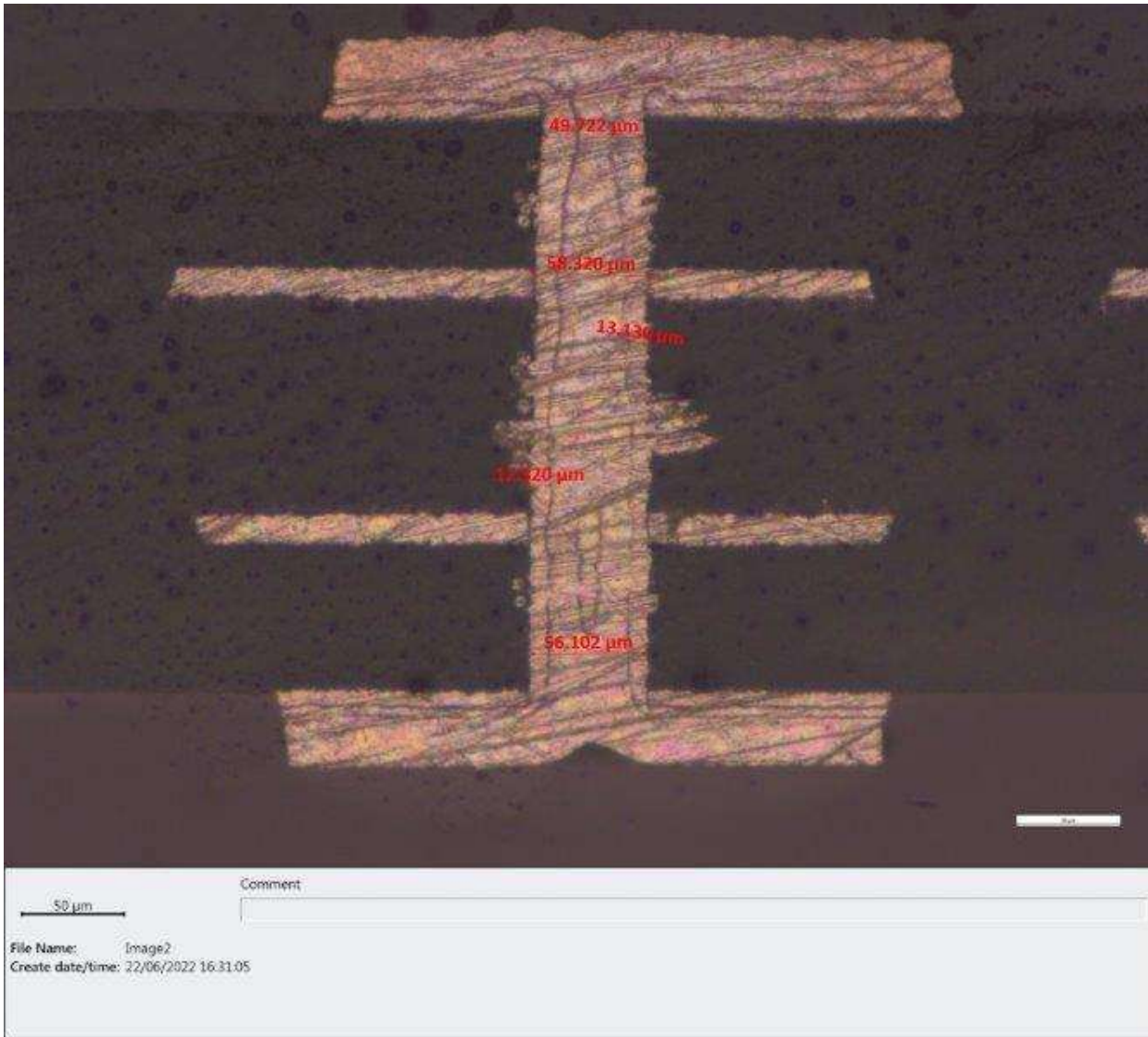
***Eltek offers another advancement in miniaturization.***

Eltek is pleased to update our customers on achieving another milestone as part of the technological development that enables the production of thin and dense circuits.

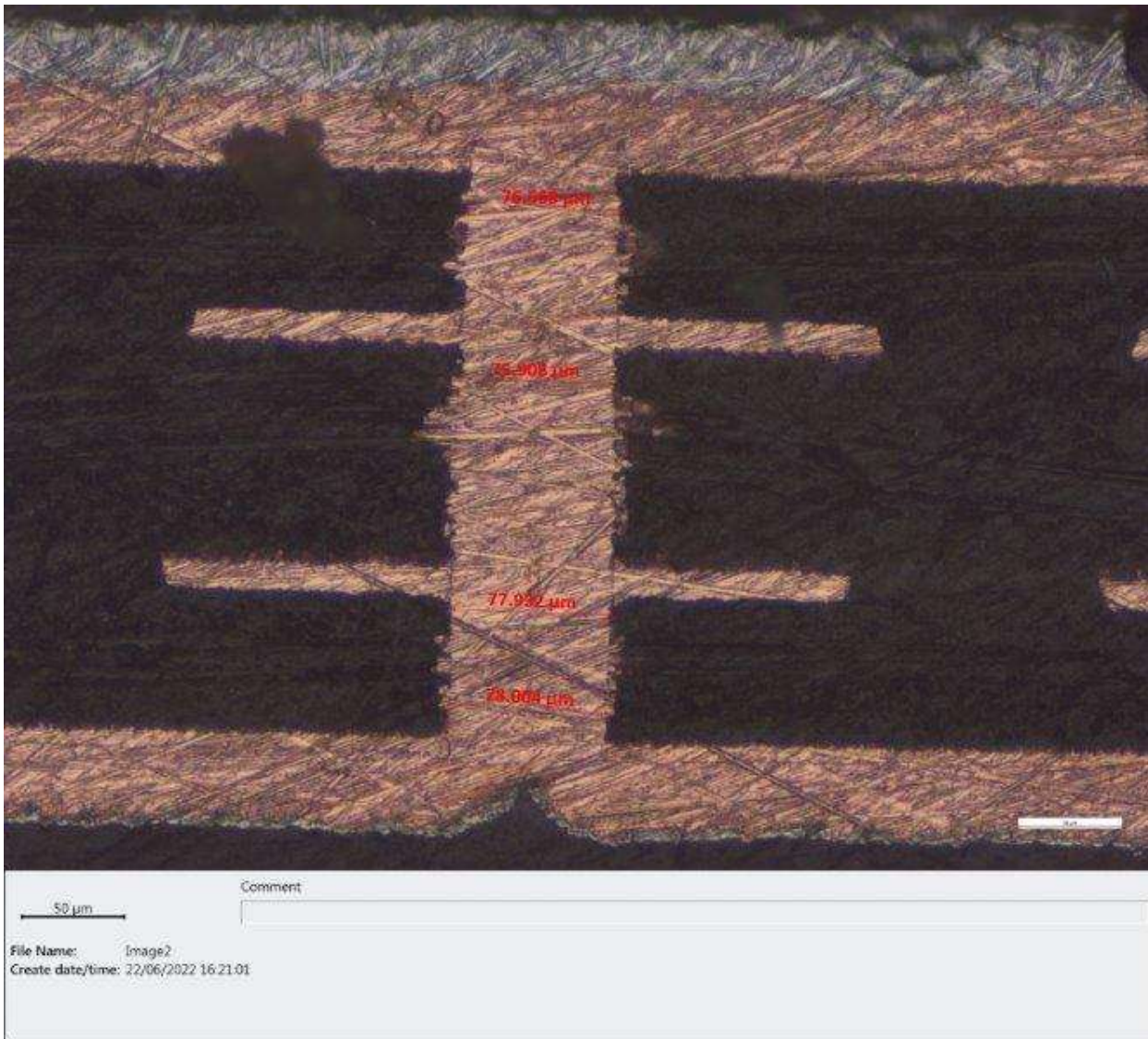
Eltek's development program includes the development of an additive method, MSAP / SAP and the ability to drill and coat small through holes diameters of up to 50  $\mu$ .

In addition, Eltek has successfully completed the development process of through hole coating and copper filling. *See Figures 1 and 2.*

This pcb technology allow Eltek to support customers with increased functionality of their pcb design in a reduced area, taking advantage of the industry trend in miniaturization of semiconductors and other component packages.



**Figure 1- Mechanical Drilling 2 mil**



**Figure 2- Mechanical Drilling 3 mil**